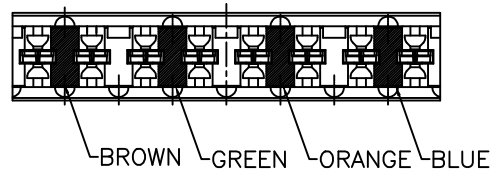
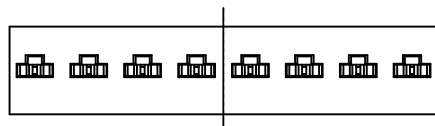
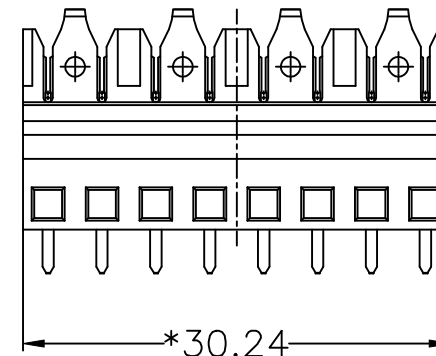
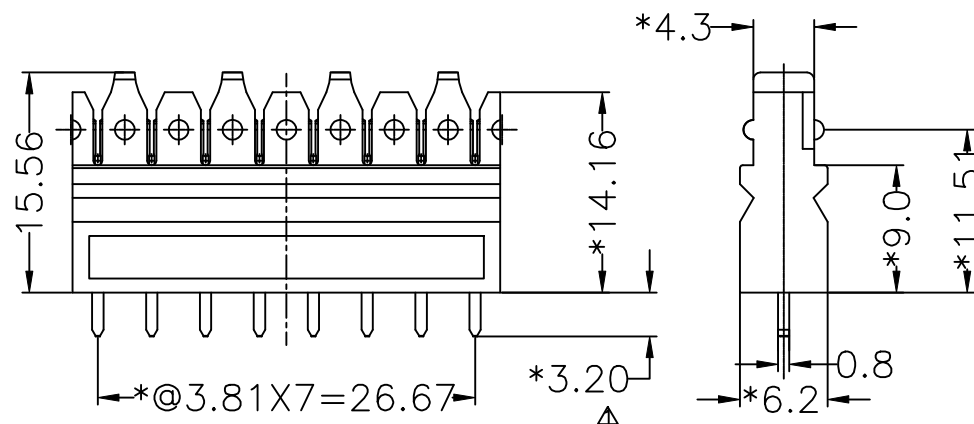


REVISION RECORD				
REV	ECO	DESCRIPTION	DRFT	CHKD
△		drawing modify	LHB 2005/10/29	



7- $\phi 1.20$ $\rightarrow @3.81 \times 7 = 26.67 \rightarrow$

PCB LAYOUT

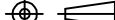


NOTE:

- 1.HOUSING:PC UL94-0
- 2.CONTACT:PHOSPHOR BRONZE WITH SILVER, NICKEL OR TIN PLATING
- 3.CABLE SIZE:
WITH WIRES: 24# AWG
- 4.CONTACT RESISTANCE: 10MILLIOHMS MAX
- 5.VOLTAGE RATING: 250VDC
- 6.OPERATING TEMPERATURE: -20°TO +125°C AND HUMLDITY UP TO 95%
- 7.INSULATION RESISTANCE:500VDC,VOLTAGE APPLIED 1000MEGOHMS MIN
- 8.DIELECTRIC STRENGTH :AC 1000VRMS
- 9.PART NUMBER: E4808--Q0061X-L

110 IDC(ADVANCED)

A-TIN PLATE
B-NICKEL PLATE
F-SILVER PLATE

DETACHED LISTS	MM (INCH)		DFTO SCC	DATE 9/07/05*	FULL RISE ELECTRONIC CO., LTD		
	TOLERANCES EXCEPT AS NOTED		CHKDZY	DATE2005/10/31			
			MFO	DATE	TITLE IDC-8P(Advanced) With Color		
			APPVL-SAMMY	DATE 2005/10/31			
					DRAWING NO. GE483125-LC		
	MATERIAL :				SIZE A3		
	ANGLES ±		QT'Y :		10/29/05		
			FINISH :				
THIRD ANGLE PROJECTION		SCALE : 1:1		SHEET X OF Y			